

Title (en)

CMP METHOD FOR METAL-CONTAINING SUBSTRATES

Title (de)

CMP-VERFAHREN FÜR METALLHALTIGE SUBSTRATE

Title (fr)

PROCÉDÉ CMP APPLICABLE AUX SUBSTRATS CONTENANT DU MÉTAL

Publication

EP 2052048 A4 20120118 (EN)

Application

EP 07796716 A 20070706

Priority

- US 2007015555 W 20070706
- US 83023306 P 20060712

Abstract (en)

[origin: WO2008008282A1] An aqueous chemical-mechanical polishing composition for polishing metal containing substrates comprising an abrasive particle consisting essentially of a primary particle modified with an aluminosilicate layer, and wherein the abrasive particle has a zeta potential measured at pH 2.3 of about -5 mV to about -100mV. The composition can be used to polish the surface of a tungsten containing substrate.

IPC 8 full level

C09K 3/14 (2006.01); **C09G 1/02** (2006.01); **H01L 21/321** (2006.01)

CPC (source: EP KR US)

C09G 1/02 (2013.01 - EP US); **C09K 3/14** (2013.01 - KR); **C09K 3/1436** (2013.01 - US); **C09K 3/1445** (2013.01 - EP US); **H01L 21/3212** (2013.01 - EP US)

Citation (search report)

- [X] US 2004006924 A1 20040115 - SCOTT BRANDON SHANE [US], et al & EP 2048208 A2 20090415 - DUPONT AIR PROD NANOMATERIALS [US]
- [A] JP 3776252 B2 20060517
- [AP] WO 2006133249 A2 20061214 - ADVANCED TECH MATERIALS [US], et al
- [A] US 3745126 A 19730710 - MOORE E
- See references of WO 2008008282A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2008008282 A1 20080117; CN 101490200 A 20090722; CN 101490200 B 20120905; EP 2052048 A1 20090429; EP 2052048 A4 20120118; EP 2052048 B1 20180124; IL 196222 A0 20090922; IL 196222 A 20141231; JP 2009543375 A 20091203; JP 5426373 B2 20140226; KR 101325409 B1 20131104; KR 20090029794 A 20090323; MY 153666 A 20150313; SG 173361 A1 20110829; US 2009314744 A1 20091224; US 9074118 B2 20150707

DOCDB simple family (application)

US 2007015555 W 20070706; CN 200780026307 A 20070706; EP 07796716 A 20070706; IL 19622208 A 20081225; JP 2009519467 A 20070706; KR 20097000437 A 20070706; MY PI20090113 A 20070706; SG 2011050010 A 20070706; US 30921207 A 20070706